

T-35-25

TOPAZ

SEMICONDUCTOR

SD1127

N-CHANNEL ENHANCEMENT-MODE VERTICAL D-MOS FET ULTRA LOW-LEAKAGE

ORDERING INFORMATION

TO-226AA (TO-92) Plastic Package	SD1127BD
Sorted Chips in Waffle Pack	SD1127CHP
Description	60 Volt, 4.0 ohm

FEATURES

- Drain-Source Leakage (I_{DSS}), 1.0nA max
- Low Output and Transfer Capacitances
- Extended Safe Operating Area

APPLICATIONS

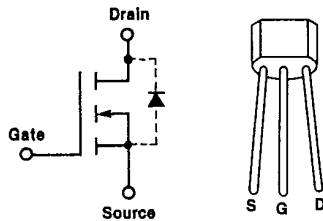
- High-Speed Switches
- Low-Leakage Solid State Relays
- High-Speed Pulse Amplifiers
- Logic Interfaces
- Line Drivers

ABSOLUTE MAXIMUM RATINGS ($T_A = +25^\circ\text{C}$ unless otherwise noted)

Drain-Source Voltage	+60V	
Drain-Gate Voltage ($V_{GS} = 0$)	+60V	
Gate-Source Voltage	$\pm 30V$	
Continuous Drain Current	$T_A = +25^\circ\text{C}$	$T_C = +25^\circ\text{C}$
	SD1127BD .20A	.36A
Peak Pulsed Drain Current	2.0A	

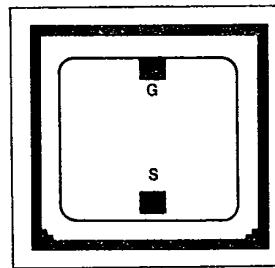
Continuous Device Dissipation	$T_A = +25^\circ\text{C}$	$T_C = +25^\circ\text{C}$
	SD1127BD 0.30W	1.0W
Linear Derating Factor	$T_A = +25^\circ\text{C}$	$T_C = +25^\circ\text{C}$
	SD1127BD 3.0mW/ $^\circ\text{C}$	10mW/ $^\circ\text{C}$
Operating Junction and Storage Temperature Range	-55 $^\circ\text{C}$ to +150 $^\circ\text{C}$	
Lead Temperature (1/16" from mounting surface for 30 sec.)	+260 $^\circ\text{C}$	

PIN CONFIGURATION



PACKAGE DIMENSIONS (TO-92) TO-226AA (See Package 5)

CHIP CONFIGURATION



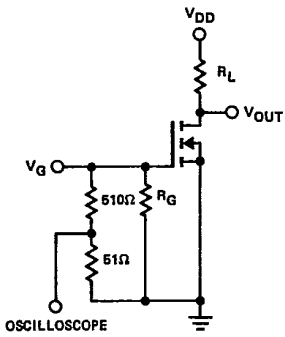
Dimensions: 054 x .051 x .020 in.
Drain is backside contact.

ELECTRICAL CHARACTERISTICS ($T_A = +25^\circ\text{C}$ unless otherwise noted)

#	CHARACTERISTIC	SD1127			UNIT	TEST CONDITION
		MIN	TYP	MAX		
1	BV_{DSS} Drain-Source Breakdown Voltage	60	90		V	$I_D = 10\mu\text{A}, V_{GS} = 0$
2	$V_{GS(th)}$ Gate-Source Threshold Voltage	0.8		2.4	V	$V_{DS} = V_{GS}, I_D = 1\text{mA}$
3	I_{GBS} Gate-Body Leakage Current		.03	1.0	nA	$V_{GS} = 20\text{V}, V_{DS} = 0$ $T_A = +125^\circ\text{C}$
4				10		
5	I_{DSS} Drain-Source OFF Leakage Current			1.0	nA	$V_{DS} = 30\text{V}, V_{GS} = 0$ $T_A = +125^\circ\text{C}$
6				100		
7	$I_{D(on)}$ ON Drain Current	2.0	3.5		A	$V_{DS} = 25\text{V}, V_{GS} = 10\text{V}$ (Note 1)
8	$r_{DS(on)}$ Drain-Source ON Resistance		3.2	5.0	ohms	$V_{GS} = 5\text{V}, I_D = 0.3\text{A}$ (Note 1)
9				2.9	4.0	$V_{GS} = 10\text{V}, I_D = 1.0\text{A}$ (Note 1)
10	g_{fs} Common-Source Forward Transcond.	250	500		mmhos	$V_{DS} = 25\text{V}, I_D = 1.0\text{A}$ $f = 1\text{KHz}$ (Note 1)
11	C_{iss} Common-Source Input Capacitance		80		pF	$V_{DS} = 25\text{V}, V_{GS} = 0$ $f = 1\text{MHz}$
12	C_{rss} Common-Source Reverse Transfer Capacitance		1.5			
13	C_{oss} Common-Source Output Capacitance		15			
14	t_{on} Turn-On Time		4.0	6.0	nSec	$V_{DD} = 25\text{V}$ $R_L = 25\text{ ohms}$ $R_G = 51\text{ ohms}$ $V_{G(on)} = 10\text{V}$
15	t_{off} Turn-Off Time		4.0	6.0		

Note 1: Pulse Test 80µSec, 1% Duty Cycle

SWITCHING TIMES TEST CIRCUIT



INPUT PULSE
 $t_r < 0.6\text{ nSEC}$
PULSE WIDTH - 100 nSEC

SAMPLING OSCILLOSCOPE
 $t_r < 0.38\text{ nSEC}$
 $R_{in} > 1\text{M}\Omega$
 $C_{in} < 2.0\text{ pF}$

TEST WAVEFORMS

